



## PIN DESCRIPTIONS

PIN (DIP & SOIC)	SYMBOL	FUNCTION	DESCRIPTION
1	VDDA	power supply	+3.3 volt power for channel A
2	BUSA	analog output	MIL-STD-1533 bus driver A, positive signal
3	$\overline{BUSA}$	analog output	MIL-STD-1553 bus driver A, negative signal
4	RXENA	digital input	Receiver A enable. If low, forces RXA and $\overline{RXA}$ low (HI-1573) or High (HI-1574)
5	GNDA	power supply	Ground for channel A
6	Vddb	power supply	+3.3 volt power for channel B
7	BUSB	analog output	MIL-STD-1533 bus driver B, positive signal
8	$\overline{BUSB}$	analog output	MIL-STD-1553 bus driver B, negative signal
9	RXENB	digital input	Receiver B enable. If low, forces RXB and $\overline{RXB}$ low (HI-1573) or High (HI-1574)
10	GNDB	power supply	Ground for channel B
11	$\overline{RXB}$	digital output	Receiver B output, inverted
12	RXB	digital output	Receiver B output, non-inverted
13	TXINHB	digital input	Transmit inhibit, channel B. If high BUSB, $\overline{BUSB}$ disabled
14	TXB	digital input	Transmitter B digital data input, non-inverted
15	$\overline{TXB}$	digital input	Transmitter B digital data input, inverted
16	$\overline{RXA}$	digital output	Receiver A output, inverted
17	RXA	digital output	Receiver A output, non-inverted
18	TXINHA	digital input	Transmit inhibit, channel A. If high BUSA, $\overline{BUSA}$ disabled
19	TXA	digital input	Transmitter A digital data input, non-inverted
20	$\overline{TXA}$	digital input	Transmitter A digital data input, inverted

## FUNCTIONAL DESCRIPTION

The HI-1573 family of data bus transceivers contains differential voltage source drivers and differential receivers. They are intended for applications using a MIL-STD-1553 A/B data bus. The device produces a trapezoidal output waveform during transmission.

### TRANSMITTER

Data input to the device's transmitter section is from the complementary CMOS inputs TXA/B and  $\overline{TXA/B}$ . The transmitter accepts Manchester II bi-phase data and converts it to differential voltages on BUSA/B and  $\overline{BUSA/B}$ . The transceiver outputs are either direct or transformer coupled to the MIL-STD-1553 data bus. Both coupling methods produce a nominal voltage on the bus of 7.5 volts peak to peak.

The transmitter is automatically inhibited and placed in the high impedance state when both TXA/B and  $\overline{TXA/B}$  are either at a logic "1" or logic "0" simultaneously. A logic "1" applied to the TXINHA/B input will force the transmitter to the high impedance state, regardless of the state of TXA/B and  $\overline{TXA/B}$ .

### RECEIVER

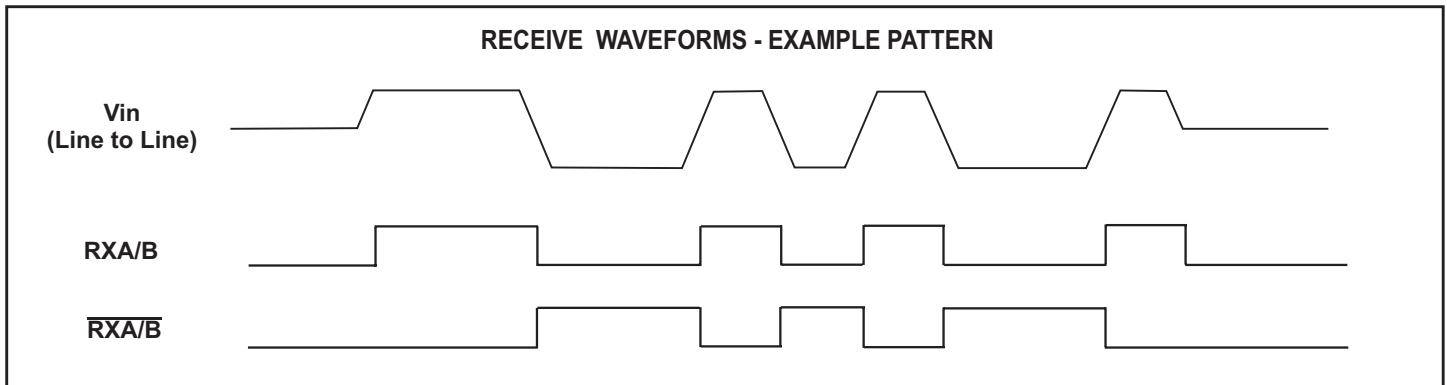
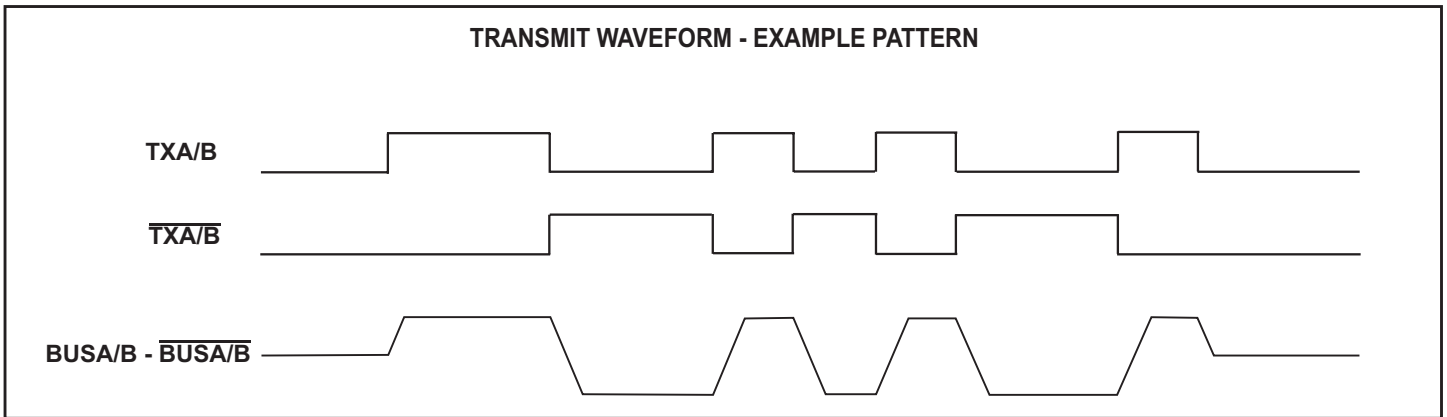
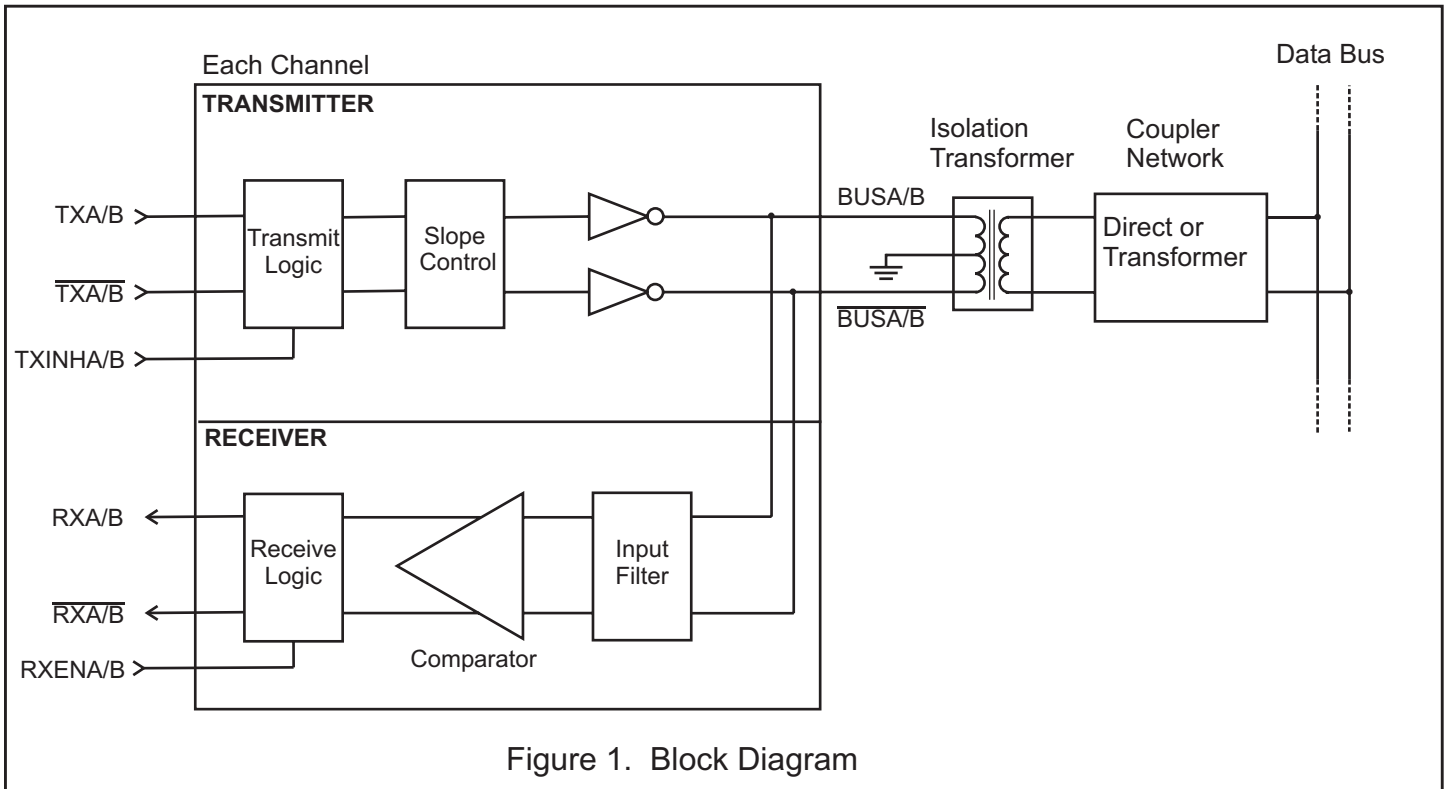
The receiver accepts bi-phase differential data from the MIL-STD-1553 bus through the same direct or transformer coupled interface as the transmitter. The receiver's differential input stage drives a filter and threshold comparator that produces CMOS data at the RXA/B and  $\overline{RXA/B}$  output pins.

Each set of receiver outputs can be independently forced to a logic "0" (HI-1573) or logic "1" (HI-1574) by setting RXENA or RXENB low.

### MIL-STD-1553 BUS INTERFACE

A direct coupled interface (see Figure 2) uses a 1:2.5 ratio isolation transformer and two 55 ohm isolation resistors between the transformer and the bus.

In a transformer coupled interface (see Figure 3), the transceiver is connected to a 1:1.79 isolation transformer which in turn is connected to a 1:1.4 coupling transformer. The transformer coupled method also requires two coupling resistors equal to 75% of the bus characteristic impedance ( $Z_0$ ) between the coupling transformer and the bus.



**ABSOLUTE MAXIMUM RATINGS**

Supply voltage (VDD)	-0.3 V to +5 V
Logic input voltage range	-0.3 V dc to +3.6 V
Receiver differential voltage	10 Vp-p
Driver peak output current	+1.0 A
Power dissipation at 25°C ceramic DIL, derate	1.0 W 7mW/°C
Solder Temperature	275°C for 10 sec.
Junction Temperature	175°C
Storage Temperature	-65°C to +150°C

**RECOMMENDED OPERATING CONDITIONS**

Supply Voltage
VDD..... 3.3V... ±5%
Temperature Range
Industrial Screening.....-40°C to +85°C
Hi-Temp Screening.....-55°C to +125°C
Military Screening.....-55°C to +125°C

*NOTE: Stresses above absolute maximum ratings or outside recommended operating conditions may cause permanent damage to the device. These are stress ratings only. Operation at the limits is not recommended.*

**DC ELECTRICAL CHARACTERISTICS**

VDD = 3.3 V, GND = 0V, TA = Operating Temperature Range (unless otherwise specified).

PARAMETER	SYMBOL	CONDITION	MIN	TYP	MAX	UNITS	
Operating Voltage	VDD		3.15	3.30	3.45	V	
Total Supply Current	ICC1	Not Transmitting		4	10	mA	
	ICC2	Transmit one channel @ 50% duty cycle		225	250	mA	
	ICC3	Transmit one channel @ 100% duty cycle		425	500	mA	
Power Dissipation	PD1	Not Transmitting			0.06	W	
	PD2	Transmit one channel @ 100% duty cycle		0.3	0.5	W	
Min. Input Voltage (HI)	V <sub>IH</sub>	Digital inputs	70%			VDD	
Max. Input Voltage (LO)	V <sub>IL</sub>	Digital inputs			30%	VDD	
Min. Input Current (HI)	I <sub>IH</sub>	Digital inputs			20	µA	
Max. Input Current (LO)	I <sub>IL</sub>	Digital inputs	-20			µA	
Min. Output Voltage (HI)	V <sub>OH</sub>	I <sub>OUT</sub> = -1.0mA, Digital outputs	90%			VDD	
Max. Output Voltage (LO)	V <sub>OL</sub>	I <sub>OUT</sub> = 1.0mA, Digital outputs			10%	VDD	
<b>RECEIVER (Measured at Point "Ad" in Figure 2 unless otherwise specified)</b>							
Input resistance	R <sub>IN</sub>	Differential	20			Kohm	
Input capacitance	C <sub>IN</sub>	Differential			5	pF	
Common mode rejection ratio	CMRR		40			dB	
Input Level	V <sub>IN</sub>	Differential			9	Vp-p	
Input common mode voltage	V <sub>ICM</sub>		-5.0		5.0	V-pk	
Threshold Voltage - Direct-coupled	Detect	V <sub>THD</sub>	1 Mhz Sine Wave (Measured at Point "Ad" in Figure 2)	1.15		20.0	Vp-p
	No Detect	V <sub>THND</sub>				0.28	Vp-p
Theshold Voltage - Transformer-coupled	Detect	V <sub>THD</sub>	1 MHz Sine Wave (Measured at Point "At" in Figure 3)	0.86		14.0	Vp-p
	No Detect	V <sub>THND</sub>				0.20	Vp-p

## DC ELECTRICAL CHARACTERISTICS (cont.)

VDD = 3.3 V, GND = 0V, TA = Operating Temperature Range (unless otherwise specified).

PARAMETER	SYMBOL	CONDITION	MIN	TYP	MAX	UNITS	
<b>TRANSMITTER (Measured at Point "Ad" in Figure 2 unless otherwise specified)</b>							
Output Voltage	Direct coupled	V <sub>OUT</sub>	35 ohm load (Measured at Point "Ad" in Figure 2)	6.0		9.0	Vp-p
	Transformer coupled	V <sub>OUT</sub>	70 ohm load (Measured at Point "At" in Figure 3)	18.0		27.0	Vp-p
Output Noise		V <sub>ON</sub>	Differential, inhibited			10.0	mVp-p
Output Dynamic Offset Voltage	Direct coupled	V <sub>DYN</sub>	35 ohm load (Measured at Point "Ad" in Figure 2)	-90		90	mV
	Transformer coupled	V <sub>DYN</sub>	70 ohm load (Measured at Point "At" in Figure 3)	-250		250	mV
Output resistance		R <sub>OUT</sub>	Differential, not transmitting	10			Kohm
Output Capacitance		C <sub>OUT</sub>	1 MHz sine wave			15	pF

## AC ELECTRICAL CHARACTERISTICS

VDD = 3.3 V, GND = 0V, TA = Operating Temperature Range (unless otherwise specified).

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
<b>RECEIVER (Measured at Point "Ad" in Figure 2)</b>						
Receiver Delay	t <sub>DR</sub>	From input zero crossing to RXA/B or $\overline{RXA/B}$			450	ns
Receiver Enable Delay	t <sub>REN</sub>	From RXENA/B rising or falling edge to RXA/B or $\overline{RXA/B}$			40	ns
<b>TRANSMITTER (Measured at Point "Ad" in Figure 2)</b>						
Driver Delay	t <sub>DT</sub>	TXA/B, TXA/B to BUSA/B, BUSA/B			150	ns
Rise time	t <sub>r</sub>	35 ohm load	100		300	ns
Fall Time	t <sub>f</sub>	35 ohm load	100		300	ns
Inhibit Delay	t <sub>DI-H</sub>	Inhibited output			100	ns
	t <sub>DI-L</sub>	Active output			150	ns

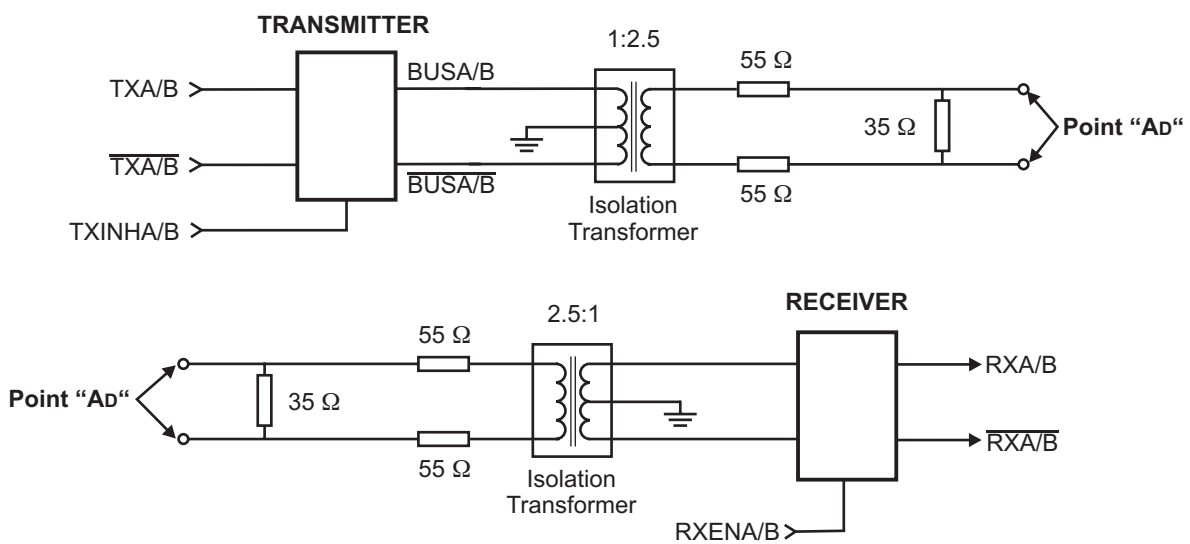


Figure 2. Direct Coupled Test Circuits

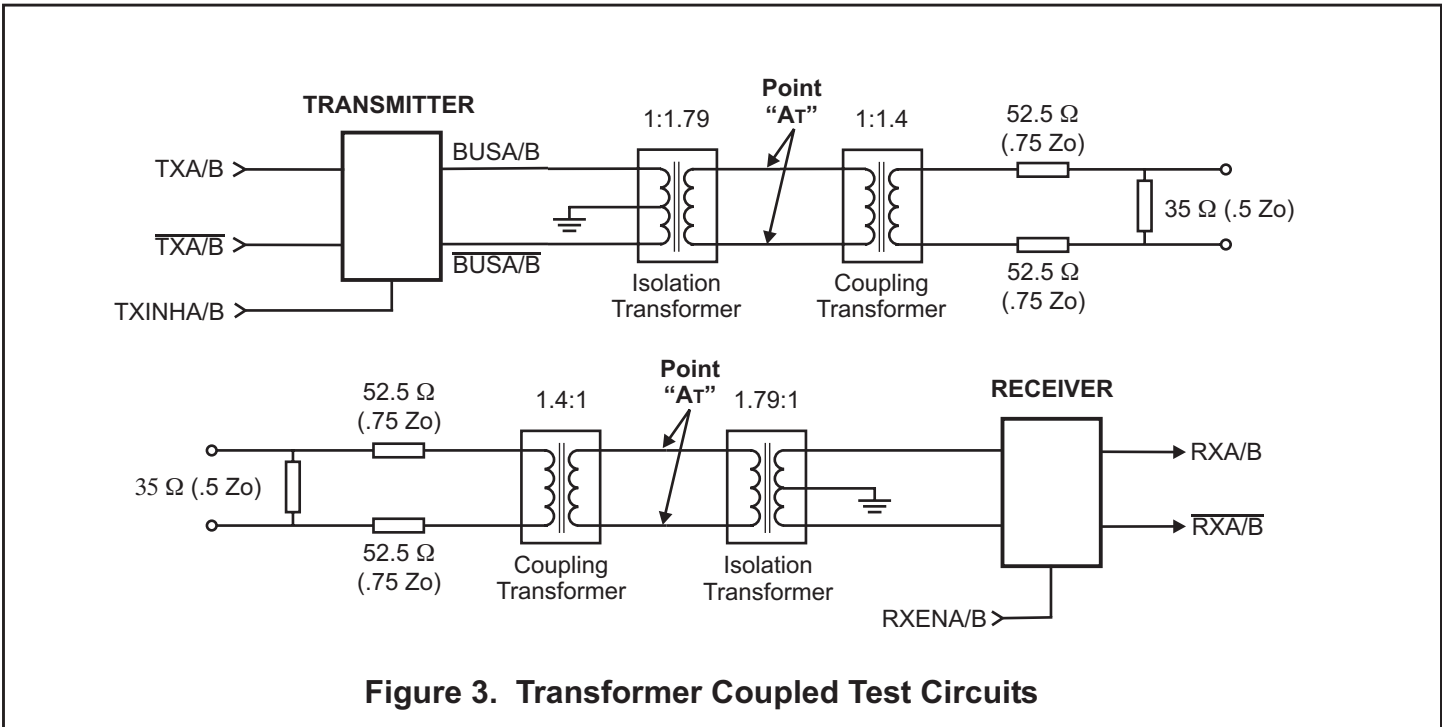


Figure 3. Transformer Coupled Test Circuits

**HEAT SINK - ESOIC & CHIP-SCALE PACKAGE APPLICATIONS NOTE**

Both the HI-1573PSI/T/M and HI-1574PSI/T/M use a 20-pin thermally enhanced SOIC package. The HI-1573PCI/T and HI-1574PCI/T use a plastic chip-scale package. These packages include a metal heat sink located on the bottom surface of the device. This heat sink should be soldered down to the printed circuit board for optimum thermal dissipation. The heat sink is electrically isolated and may be soldered to any convenient power or ground plane..

Holt Applications Note AN-500 provides circuit design notes regarding the use of Holt's family of MIL-STD-1553 transceivers. Layout considerations, as well as recommended interface and protection components are included.

**THERMAL CHARACTERISTICS**

PART NUMBER	PACKAGE STYLE	CONDITION	θ <sub>JA</sub>	JUNCTION TEMPERATURE		
				T <sub>A</sub> =25°C	T <sub>A</sub> =85°C	T <sub>A</sub> =125°C
HI-1573PSI / T / M	20-pin Thermally enhanced plastic SOIC (ESOIC)	Heat sink unsoldered	54°C/W	52°C	112°C	152°C
HI-1574PSI / T / M		Heat sink soldered	47°C/W	49°C	109°C	149°C
HI-1573CDI / T / M HI-1574CDI / T / M	20-pin Ceramic side-brazed DIP	Socketed	62°C/W	56°C	116°C	156°C
HI-1573PCI / T HI-1574PCI / T	44-pin Plastic chip-scale package	Heat sink unsoldered	49°C/W	50°C	110°C	150°C

Data taken at VDD=3.3V, continuous transmission at 1Mbit/s, single transmitter enabled.

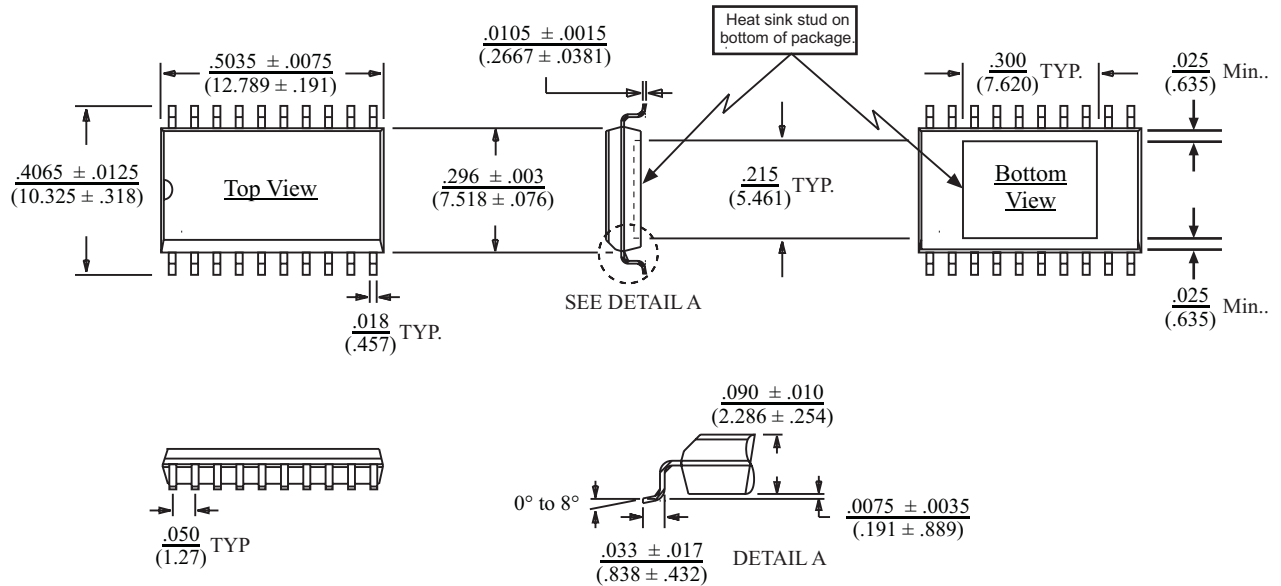
## ORDERING INFORMATION

PART NUMBER	IDLE STATE	PACKAGE DESCRIPTION	TEMPERATURE RANGE	PROCESS FLOW	BURN IN	LEAD FINISH
HI-1573PSI	0	20 PIN PLASTIC ESOIC - WB	-40°C TO +85°C	I	NO	SOLDER
HI-1573PST	0	20 PIN PLASTIC ESOIC - WB	-55°C TO +125°C	T	NO	SOLDER
HI-1573PSM	0	20 PIN PLASTIC ESOIC - WB	-55°C TO +125°C	M	YES	SOLDER
HI-1573CDI	0	20 PIN CERAMIC SIDE BRAZED DIP	-40°C TO +85°C	I	NO	GOLD
HI-1573CDT	0	20 PIN CERAMIC SIDE BRAZED DIP	-55°C TO +125°C	T	NO	GOLD
HI-1573CDM	0	20 PIN CERAMIC SIDE BRAZED DIP	-55°C TO +125°C	M	YES	SOLDER
HI-1573PCI	0	44 PIN CHIP SCALE PACKAGE	-40°C TO +85°C	I	NO	SOLDER
HI-1573PCT	0	44 PIN CHIP SCALE PACKAGE	-55°C TO +125°C	T	NO	SOLDER
HI-1574PSI	1	20 PIN PLASTIC ESOIC - WB	-40°C TO +85°C	I	NO	SOLDER
HI-1574PST	1	20 PIN PLASTIC ESOIC - WB	-55°C TO +125°C	T	NO	SOLDER
HI-1574PSM	1	20 PIN PLASTIC ESOIC - WB	-55°C TO +125°C	M	YES	SOLDER
HI-1574CDI	1	20 PIN CERAMIC SIDE BRAZED DIP	-40°C TO +85°C	I	NO	GOLD
HI-1574CDT	1	20 PIN CERAMIC SIDE BRAZED DIP	-55°C TO +125°C	T	NO	GOLD
HI-1574CDM	1	20 PIN CERAMIC SIDE BRAZED DIP	-55°C TO +125°C	M	YES	SOLDER
HI-1574PCI	1	44 PIN CHIP SCALE PACKAGE	-40°C TO +85°C	I	NO	SOLDER
HI-1574PCT	1	44 PIN CHIP SCALE PACKAGE	-55°C TO +125°C	T	NO	SOLDER

Legend: ESOIC - Thermally Enhanced Small Outline Package (SOIC w/built-in heat sink)  
 WB - Wide Body

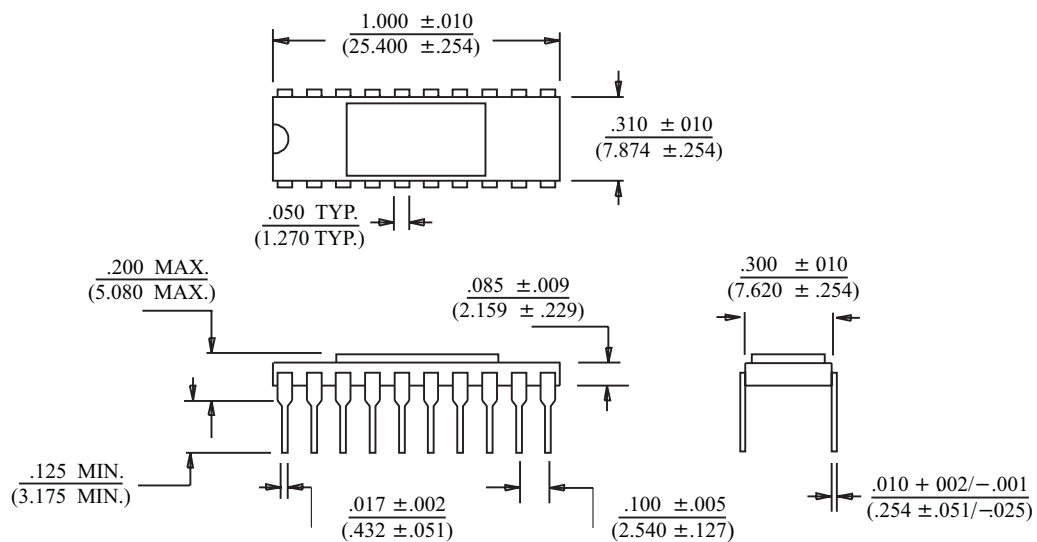
**20-PIN PLASTIC SMALL OUTLINE (ESOC) - WB**  
(Wide Body, Thermally Enhanced)

Package Type: 24HEW



**20-PIN CERAMIC SIDE-BRAZED DIP**

PACKAGE TYPE: 20C





**44-PIN PLASTIC CHIP-SCALE PACKAGE**

